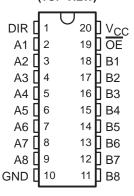
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- Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- High-Impedance State During Power Up and Power Down
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

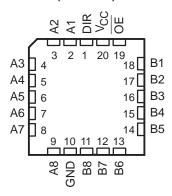
### description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so the buses are effectively isolated.

SN54ABTR2245 . . . J PACKAGE SN74ABTR2245 . . . DB, DGV, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABTR2245 . . . FK PACKAGE (TOP VIEW)



Both the A-port and B-port outputs, which are designed to sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTR2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTR2245 is characterized for operation from –40°C to 85°C.

### **FUNCTION TABLE**

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation



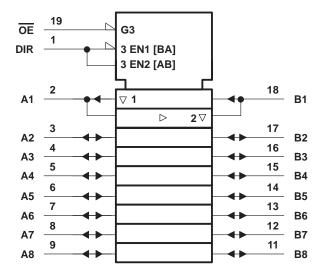
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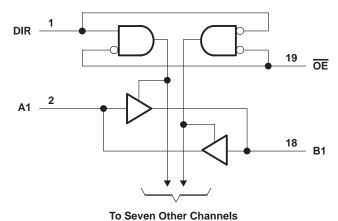
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# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

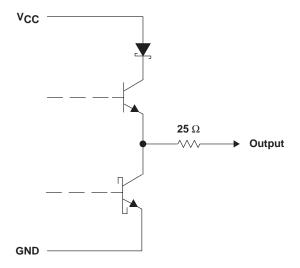
# logic diagram (positive logic)





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## output schematic



All resistor values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		
Input voltage range, VI (except I/O ports) (see I	Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high	or power-off state, VO	
Current into any output in the low state, IO		30 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )		–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		
Package thermal impedance, θ <sub>JA</sub> (see Note 2):	: DB package	115°C/W
	DGV package	146°C/W
	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

# SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

			SN54AB1	ΓR2245	SN74AB1	TR2245	LINUT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	3	2		V	
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V	
VI	Input voltage			Vcc	0	Vcc	V
IOH	High-level output current		1	-12		-12	mA
loL	Low-level output current		3	12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	0	5		5	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		2 200		200		μs/V
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

# SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COA	Т	A = 25°C	;	SN54ABTR2245		SN74ABTR2245		UNIT	
PAR	ANICIER	TEST CON	IDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNII
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	3.35			3.3		3.35		
Vон		$V_{CC} = 5 V$ ,	I <sub>OH</sub> = -1 mA	3.85			3.8		3.85		V
VОН		V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$				3		3.1		V
		VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.6					2.6		
VOL		V <sub>CC</sub> = 4.5 V	IOL = 8 mA			0.65		0.8		0.65	V
VOL		VCC = 4.0 V	I <sub>OL</sub> = 12 mA			0.8				0.8	•
V <sub>hys</sub>					100						mV
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V}, \text{ V}_{I}$	= V <sub>CC</sub> or GND			±1		±1		±1	μΑ
l <sub>l</sub>	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_I = V_{CC} \text{ or GND}$			±20		±20		±20	μΑ	
lozH <sup>‡</sup>		$\frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}$			10		10		10	μΑ	
l <sub>OZL</sub> ‡		$\frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}$			-10	,	-10		-10	μΑ	
lozpu§	}	$\frac{\text{VCC}}{\text{OE}} = 0 \text{ to } 2.1 \text{ V, V}_{\text{O}}$	) = 0.5 V to 2.7 V,			±50	300%	±50		±50	μΑ
I <sub>OZPD</sub> §	i	$\frac{V_{CC}}{OE} = 2.1 \text{ V to } 0, V_{O} = 0.5 \text{ V to } 2.7$				±50	Q	±50		±50	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
IOI		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-25		-100	-25	-100	-25	-100	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high		1	250		250		250	μΑ
ICC	A or B ports	$I_{O} = 0$ ,	Outputs low		24	32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ
	Data insute	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
∆lcc#	Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		0.05		0.05	mA
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5	
Ci		V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
C <sub>io</sub>		$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			6						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

<sup>§</sup> This parameter is characterized but not production tested.

<sup>¶</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

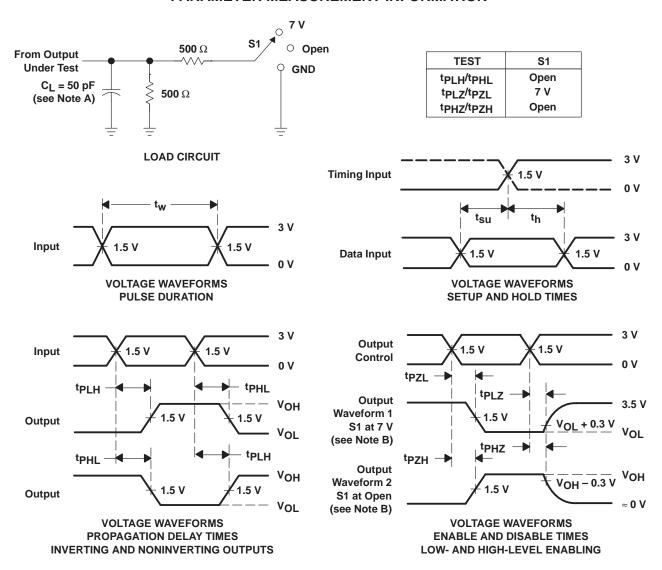
# SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(	CC = 5 V 4 = 25°C	', ;	SN54ABT	R2245	SN74AB1	R2245	UNIT
	(INFOT)	(0011-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	P.or A	1	2.5	3.4	1	4	1	3.8	20
<sup>t</sup> PHL	AUIB	B or A	1	3.2	4.2	1 (	4.6	1	4.5	ns
<sup>t</sup> PZH	ŌĒ	A or B	1.5	3.6	4.9	1.5	6.3	1.5	6.1	20
t <sub>PZL</sub>	OE	AUIB	1.5	3.9	5.3	1.5	6.6	1.5	6.3	ns
<sup>t</sup> PHZ	<del></del>	A or P	1.5	3.6	4.7	1.5	5.5	1.5	5.3	20
t <sub>PLZ</sub>	OE A or B		1.5	3.3	4.4	1.5	4.9	1.5	4.8	ns

### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} \leq$  2.5 ns,  $t_{f} \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

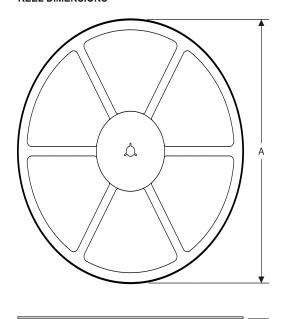
Figure 1. Load Circuit and Voltage Waveforms

# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**



### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTR2245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABTR2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABTR2245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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\*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTR2245DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ABTR2245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABTR2245PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

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